Flexible Thermal Ground Plane with Micro/Nano-Scaled Wicking Structure (FTGP)

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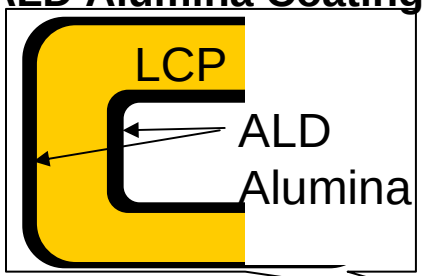
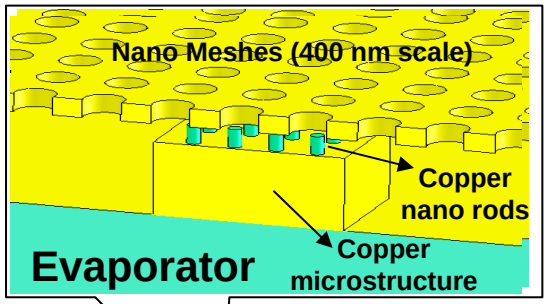
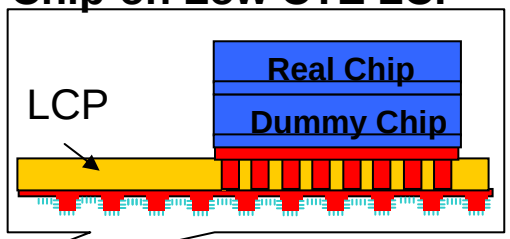
1. Hermeticity:
Liquid Crystal Polymer (LCP)
ALD Alumina Coating

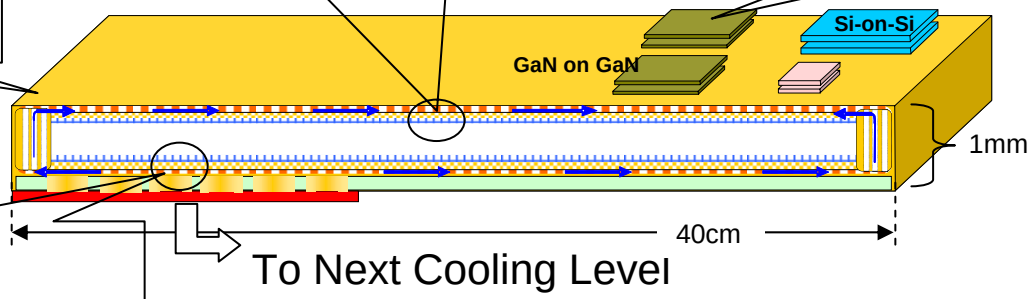


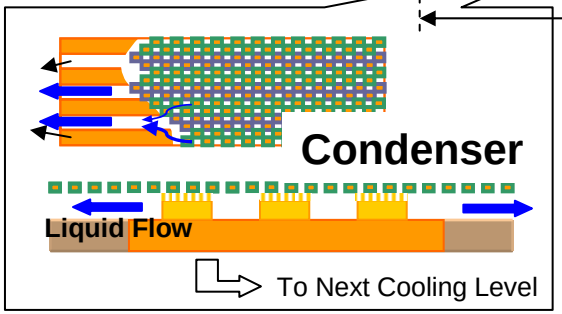
2. Wicking: Micro/Nano Fins + ALD Hydrophilic Coating

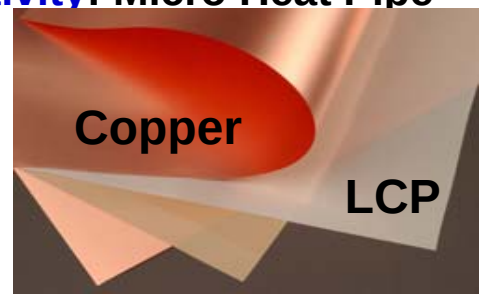


3. Thermal Expansion Mismatch: Chip-on-Chip-on Low CTE LCP







2. Wicking:
Micro/Nano Fins + ALD Hydrophobic Coating

4. Wick Thermal Conductivity: Copper Fins
5. TGP Thermal Conductivity: Micro Heat Pipe
6. Thickness, Area, Weight: LCP Flexible Circuits for Heat Pipe
7. Duration: Simple and Reliable